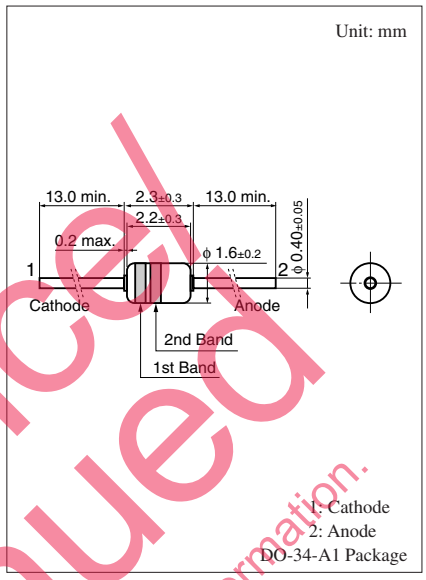
MA2C859 (MA859)

Silicon epitaxial planar type

For band switching



■ Features

- Extra-small DHD envelope, allowing to insert into a 5 mm pitch hole
- Less voltage dependence of the diode capacitance C_D
- Low forward dynamic resistance r_f
- Optimum for a band switching of tuner

■ Absolute Maximum Ratings $T_a = 25°C$

Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	35	V
Forward current	I_F	100	mA
Operating ambient temperature *	T_{opr}	−25 to +85	°C
Storage temperature	T_{stg}	−55 to +100	°C

Note) ∗: Maximum ambient temperature during operation.

■ Electrical Characteristics $T_a = 25°C \pm 3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_F	$I_F = 100$ mA			1.0	V
Reverse current *1	I_R	$V_R = 33$ V			100	nA
Diode capacitance	C_D	$V_R = 6$ V, f = 1 MHz		0.8	1.2	pF
Forward dynamic resistance *2	r_f	$I_F = 2$ mA, f = 100 MHz		0.77	0.98	Ω

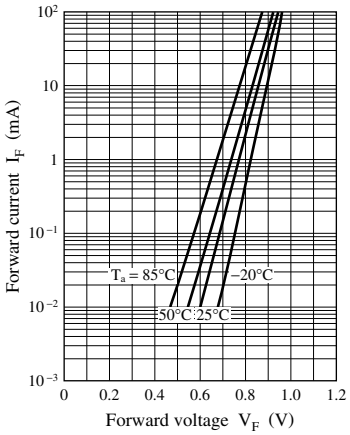
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. Absolute frequency of input and output is 100 MHz.
3. ∗1: I_R should be measured under the condition of prevention the light.
∗2: Measuring instrument; YHP MODEL 4191A RF IMPEDANCE ANALYZER

■ Cathode Mark

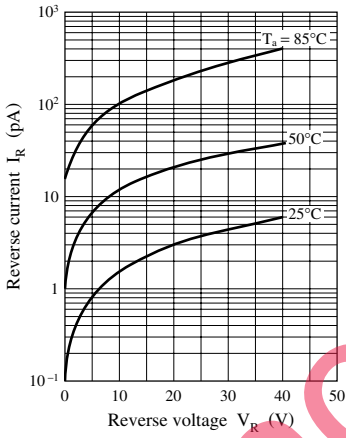
Type No.		MA2C859
Color	1st Band	Black
	2nd Band	Blue

Note) The part number in the parenthesis shows conventional part number.

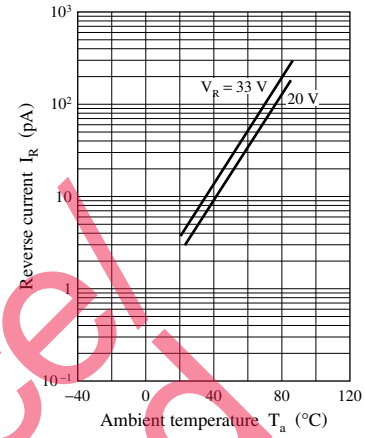
I_F — V_F



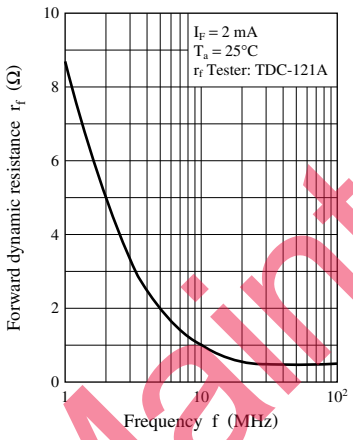
I_R — V_R



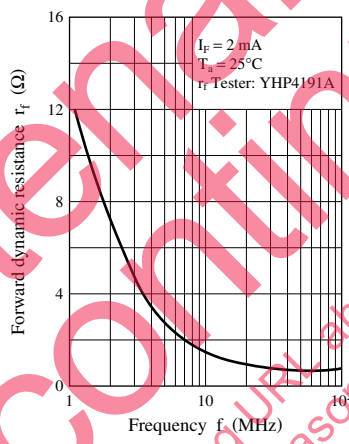
I_R — T_a



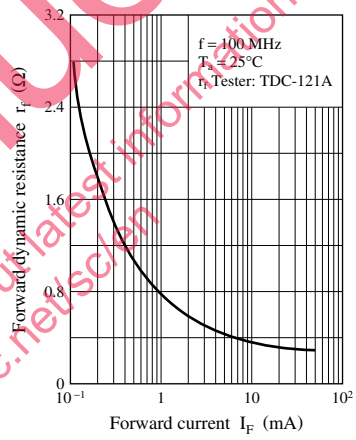
r_f — f



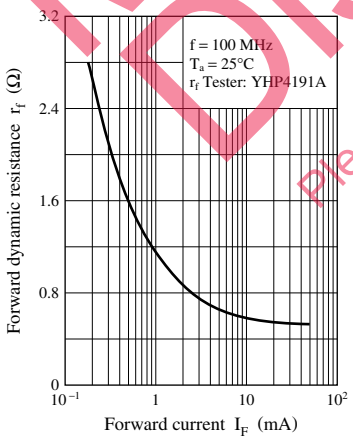
r_f — f



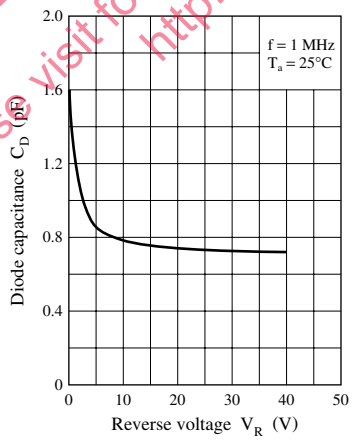
r_f — f



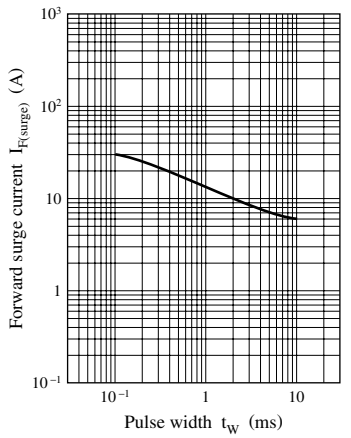
r_f — I_F



C_D — V_R



$I_{F(surge)}$ — t_W



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